

LISTING OF THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. – 39. (Cancelled)

40. (Currently Amended) A substrate processing system comprising a network having a coupling between a substrate processing apparatus discharging a processing solution onto a rotating substrate to perform predetermined processing, and a computer collecting data from said substrate processing apparatus, said substrate processing system comprising:

a collection part configured to monitor and collect a plurality of control elements in a specific step as one of processes of said predetermined processing in said substrate processing apparatus; and

an abnormality detection part configured to assess and detect a processing abnormality in said substrate processing apparatus based on a combination of said plurality of control elements collected by said collection part and to detect a processing abnormality based on the assessing.

41. (Previously Presented) The substrate processing system according to claim 40,

wherein said specific step is a discharge step discharging said processing solution onto a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality based on a combination of a plurality of control elements in said discharge step.

42. (Previously Presented) The substrate processing system according to claim 40,

wherein said substrate processing apparatus discharges a cleaning solution and thereafter discharges pure water onto a rotating substrate to perform cleaning of said substrate,

wherein said collection part monitors and collects a plurality of control elements in a cleaning solution spread step in which said cleaning solution is discharged and spread to coat a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality in said cleaning based on a combination of two or more of said plurality of control elements in said cleaning solution spread step including the number of revolutions of a substrate, the temperature, flow rate and concentration of a cleaning solution, and cleaning solution discharge time.

43. (Previously Presented) The substrate processing system according to claim 42,

wherein said collection part also monitors and collects a plurality of control elements in a pure water discharge step in which pure water is discharged onto a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality in said cleaning based on a combination of two or more of said plurality of control elements in said pure water discharge step including the number of revolutions of a substrate, the flow rate of pure water and pure water discharge time.

44. (Previously Presented) The substrate processing system according to claim 43,

wherein said cleaning solution is a polymer removal solution,

wherein said substrate processing apparatus discharges said polymer removal solution and thereafter discharges pure water onto a rotating substrate to perform polymer removal of said substrate,

wherein said collection part monitors and collects the flow rate and discharge time of a removal solution as a plurality of control elements in a removal solution spread step in which said polymer removal solution is discharged and spread to coat a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality in said polymer removal based on a combination of the flow rate and discharge time of said removal solution in said removal solution spread step.

45. (Previously Presented) The substrate processing system according to claim 43,
wherein said cleaning solution is an etching solution,
wherein said substrate processing apparatus discharges said etching solution and thereafter discharges pure water onto a rotating substrate to perform etching of said substrate,
wherein said collection part monitors and collects the concentration and discharge time of an etching solution as a plurality of control elements in an etching solution spread step in which said etching solution is discharged and spread to coat a rotating substrate, and
wherein said abnormality detection part assesses and detects a processing abnormality in said etching based on a combination of the concentration and discharge time of said etching solution in said etching solution spread step.

46. (Previously Presented) The substrate processing system according to claim 45,
wherein said etching solution is hydrofluoric acid.

47. (Previously Presented) The substrate processing system according to claim 45,
wherein said etching solution is hydrochloric acid.

48. (Previously Presented) The substrate processing system according to claim 45,
wherein said substrate processing apparatus comprises a circulation mechanism configured to collect a spent etching solution discharged once onto a substrate and to mix said spent etching solution with a new etching solution for use in circulation.

49. (Previously Presented) The substrate processing system according to claim 48,
wherein said etching solution is hydrofluoric acid.

50. (Previously Presented) The substrate processing system according to claim 48,
wherein said etching solution is hydrochloric acid.

51. (Withdrawn) A substrate processing system having coupling through a network between a substrate processing apparatus discharging a cleaning solution and thereafter discharging pure water onto a rotating substrate to performing cleaning of said substrate, and a computer collecting data from said substrate processing apparatus, said substrate processing system comprising:

an abnormality detection part for detecting a processing abnormality in said cleaning based on a combination of two or more of the number of revolutions of a substrate, the temperature, flow rate and concentration of a cleaning solution, and cleaning solution discharge time in said cleaning.

52. (Withdrawn) The substrate processing system according to claim 51,
wherein said abnormality detection part also detects a processing abnormality in said cleaning based on a combination of two or more of the number of revolutions of a substrate, the flow rate of pure water and pure water discharge time in said cleaning.

53. (Withdrawn) The substrate processing system according to claim 52,
wherein said cleaning solution is a polymer removal solution,
wherein said substrate processing apparatus discharges said polymer removal solution and thereafter discharges pure water onto a rotating substrate to perform polymer removal of said substrate, and

wherein said abnormality detection part detects a processing abnormality in said polymer removal based on a combination of the flow rate and discharge time of a removal solution in said polymer removal.

54. (Withdrawn) The substrate processing system according to claim 52,

wherein said cleaning solution is an etching solution,

wherein said substrate processing apparatus discharges said etching solution and thereafter discharges pure water onto a rotating substrate to perform etching of said substrate, and

wherein said abnormality detection part detects a processing abnormality in said etching based on a combination of the concentration and discharge time of an etching solution in said etching.

55. (Withdrawn) The substrate processing system according to claim 54, wherein said etching solution is hydrofluoric acid.

56. (Withdrawn) The substrate processing system according to claim 54, wherein said etching solution is hydrochloric acid.

57. (Currently Amended) A substrate processing apparatus discharging a processing solution onto a rotating substrate to perform predetermined processing, comprising:
a collection part configured to monitor and collect a plurality of control elements in a specific step as one of processes of said predetermined processing; and

an abnormality detection part ~~for detecting~~ configured to detect assess a processing abnormality in said processes based on a combination of said plurality of control elements collected by said collection part and to detect a processing abnormality based on the assessing.

58. (Previously Presented) The substrate processing apparatus according to claim 57, wherein said specific step is a discharge step discharging said processing solution onto a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality based on a combination of a plurality of control elements in said discharge step.

59. (Previously Presented) The substrate processing apparatus according to claim 58, wherein said predetermined processing is cleaning by discharging a cleaning solution and thereafter discharging pure water onto a rotating substrate to clean said substrate,

wherein said collection part monitors and collects a plurality of control elements in a cleaning solution spread step in which said cleaning solution is discharged and spread to coat a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality in said cleaning based on a combination of two or more of said plurality of control elements in said cleaning solution spread step including the number of revolutions of a substrate, the temperature, flow rate and concentration of a cleaning solution, and cleaning solution discharge time.

60. (Previously Presented) The substrate processing apparatus according to claim 59, wherein said collection part also monitors and collects a plurality of control elements in a pure water discharge step in which pure water is discharged onto a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality in said cleaning based on a combination of two or more of said plurality of control elements in said pure water discharge step including the number of revolutions of a substrate, the flow rate of pure water and pure water discharge time.

61. (Previously Presented) The substrate processing apparatus according to claim 60, wherein said cleaning solution is a polymer removal solution,

wherein said predetermined processing is polymer removal by discharging said polymer removal solution and thereafter discharging pure water onto a rotating substrate to clean said substrate,

wherein said collection part monitors and collects the flow rate and discharge time of a removal solution as a plurality of control elements in a removal solution spread step in which said polymer removal solution is discharged and spread to coat a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality in said polymer removal based on a combination of the flow rate and discharge time of said removal solution in said removal solution spread step.

62. (Previously Presented) The substrate processing apparatus according to claim 60, wherein said cleaning solution is an etching solution,

wherein said predetermined processing is etching by discharging said etching solution and thereafter discharging pure water onto a rotating substrate to clean said substrate,

wherein said collection part monitors and collects the concentration and discharge time of an etching solution as a plurality of control elements in an etching solution spread step in which said etching solution is discharged and spread to coat a rotating substrate, and

wherein said abnormality detection part assesses and detects a processing abnormality in said etching based on a combination of the concentration and discharge time of said etching solution in said etching solution spread step.

63. (Previously Presented) The substrate processing apparatus according to claim 62, wherein said etching solution is hydrofluoric acid.

64. (Previously Presented) The substrate processing apparatus according to claim 62, wherein said etching solution is hydrochloric acid.

65. (Previously Presented) The substrate processing apparatus according to claim 62, comprising:

a circulation mechanism configured to collect a spent etching solution discharged once onto a substrate and to mix said spent etching solution with a new etching solution for use in circulation.

66. (Previously Presented) The substrate processing apparatus according to claim 65, wherein said etching solution is hydrofluoric acid.

67. **(Previously Presented)** The substrate processing apparatus according to claim 65, wherein said etching solution is hydrochloric acid.

68. **(Withdrawn)** A substrate processing apparatus discharging a processing solution and thereafter discharging pure water onto a rotating substrate to perform cleaning of said substrate, comprising:

an abnormality detection part for detecting a processing abnormality in said cleaning based on a combination of two or more of the number of revolutions of a substrate, the temperature, flow rate and concentration of a cleaning solution, and cleaning solution discharge time in said cleaning.

69. **(Withdrawn)** The substrate processing apparatus according to claim 68, wherein said abnormality detection part also detects a processing abnormality in said cleaning based on a combination of two or more of the number of revolutions of a substrate, the flow rate of pure water and pure water discharge time in said cleaning.

70. **(Withdrawn)** The substrate processing apparatus according to claim 69, wherein said cleaning solution is a polymer removal solution, wherein said substrate processing apparatus discharges said polymer removal solution and thereafter discharges pure water onto a rotating substrate to perform polymer removal of said substrate, and

wherein said abnormality detection part detects a processing abnormality in said polymer removal based on a combination of the flow rate and discharge time of a removal solution in said polymer removal.

71. **(Withdrawn)** The substrate processing apparatus according to claim 69, wherein said cleaning solution is an etching solution, wherein said substrate processing apparatus discharges said etching solution and thereafter discharges pure water onto a rotating substrate to perform etching of said substrate, and

wherein said abnormality detection part detects a processing abnormality in said etching based on a combination of the concentration and discharge time of an etching solution in said etching.

72. **(Withdrawn)** The substrate processing apparatus according to claim 71, wherein said etching solution is hydrofluoric acid.

73. **(Withdrawn)** The substrate processing apparatus according to claim 71, wherein said etching solution is hydrochloric acid.

74. **(Withdrawn)** The substrate processing apparatus according to claim 71, comprising:

a circulation mechanism for collecting a spent etching solution discharged once onto a substrate to mix said spent etching solution with a new etching solution for use in circulation.

75. **(Withdrawn)** The substrate processing apparatus according to claim 74, wherein said etching solution is hydrofluoric acid.

76. **(Withdrawn)** The substrate processing apparatus according to claim 74, wherein said etching solution is hydrochloric acid.

77. **(Withdrawn)** A program for a computer included in a substrate processing apparatus discharging a cleaning solution and thereafter discharging pure water onto a rotating substrate to perform cleaning of said substrate,

wherein execution of said program by said computer causes said substrate processing apparatus to detect a processing abnormality in said cleaning based on a combination of two or more of the number of revolutions of a substrate, the temperature, flow rate and concentration of a cleaning solution, and cleaning solution discharge time in said cleaning.

78. (Withdrawn) A computer-readable recording medium recording a program for a computer included in a substrate processing apparatus discharging a cleaning solution and thereafter discharging pure water onto a rotating substrate to perform cleaning of said substrate, wherein execution of said program by said computer causes said substrate processing apparatus to detect a processing abnormality in said cleaning based on a combination of two or more of the number of revolutions of a substrate, the temperature, flow rate and concentration of a cleaning solution, and cleaning solution discharge time in said cleaning.